503610349 12/14/2015

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3656980

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST

CONVEYING PARTY DATA

Name	Execution Date
SEMTECH CORPORATION	10/25/2015

RECEIVING PARTY DATA

Name:	HSBC BANK USA, NATIONAL ASSOCIATION
Street Address:	660 S. FIGUEROA ST., SUITE 800
Internal Address:	ATTN: SEMTECH RELATIONSHIP MANAGER
City:	LOS ANGELES
State/Country:	CALIFORNIA
Postal Code:	90017

PROPERTY NUMBERS Total: 10

Property Type	Number
Application Number:	14824294
Application Number:	14871719
Application Number:	14827142
Application Number:	14755343
Application Number:	14767363
Application Number:	14755850
Application Number:	14810254
Application Number:	14814384
Application Number:	14825110
Application Number:	14755602

CORRESPONDENCE DATA

Fax Number: (213)443-2926

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 213-617-5493

Email: jcravitz@sheppardmullin.com

Correspondent Name: SHEPPARD, MULLIN, RICHTER & HAMPTON LLP

Address Line 1: 333 S. HOPE ST., 43RD FLOOR

Address Line 2: ATTN: J. CRAVITZ

Address Line 4: LOS ANGELES, CALIFORNIA 90071

503610349 PATENT REEL: 037284 FRAME: 0745

ATTORNEY DOCKET NUMBER:	03VV-191423
NAME OF SUBMITTER:	JULIE CRAVITZ
SIGNATURE:	/julie cravitz/
DATE SIGNED:	12/11/2015
Total Attachments: 3	

source=Semtech - Patent Security Agmt Supplement#page1.tif source=Semtech - Patent Security Agmt Supplement#page2.tif source=Semtech - Patent Security Agmt Supplement#page3.tif

> PATENT REEL: 037284 FRAME: 0746

SUPPLEMENT TO GRANT OF SECURITY INTEREST (PATENTS)

This Supplement to Grant of Security Interest (Patents) (the "Patent Security Agreement Supplement") dated as of October 25, 2015, is delivered by Semtech Corporation, a Delaware corporation ("Borrower"), Semtech New York Corporation, a Delaware corporation ("Semtech New York"), and Sierra Monolithics, Inc., a California corporation ("Sierra"; Borrower, Semtech New York and Sierra being each referred to individually herein as "Assignor", and collectively as "Assignors"), pursuant to (a) that Grant of Security Interest (Patents) dated as of May 2, 2013 (as amended, modified and supplemented to the date hereof and as the same may from time to time hereafter be further amended, modified, supplemented or restated, the "Patent Security Agreement"), by Assignors in favor of HSBC Bank USA, National Association, in its separate capacity as Administrative Agent, for the benefit of the Secured Parties, and (b) Section 5(a) of that Security Agreement dated as of May 2, 2013 (as amended, modified and supplemented to the date hereof and as the same may from time to time hereafter be further amended, modified, supplemented or restated, the "Security Agreement"), by Assignors and certain of Borrower's other direct or indirect domestic subsidiaries, jointly and severally as Grantors, in favor of HSBC Bank USA, National Association, in its separate capacity as Administrative Agent, for the benefit of the Secured Parties. Capitalized terms used but not defined herein will have the meaning ascribed to such terms in the Patent Security Agreement and/or the Security Agreement, as applicable.

The undersigned each hereby agree that (i) this Patent Security Agreement Supplement may be attached to the above-referenced Patent Security Agreement and will become and be a part thereof with the same force and effect as if originally attached thereto, and (ii) the additional Patents (as defined in the Patent Security Agreement) listed on Schedule I to this Patent Security Agreement Supplement will be and become part of the Collateral pledged by the undersigned to the Administrative Agent, for the benefit of the Secured Parties, in the Patent Security Agreement (and in the Security Agreement) with the same force and effect as if originally named therein.

The undersigned hereby certifies that the representations and warranties set forth in the Security Agreement are true and correct as to the Collateral listed herein on and as of the date hereof.

[remainder of page intentionally left blank]

~1~

SMRH:441179769.2

IN WITNESS WHEREOF, each of the parties has caused this Patent Security Agreement Supplement to be duly executed as of the date first written above.

ASSIGNORS:

SEMTECH CORPORATION, a Delaware corporation

By: Name: Charles B Adminant Title: Exe. VP + General

SEMTECH NEW YORK. a Delaware corporation

By: Name: Charles 3. Title: Eyec. VP+ General Counsel

SIERRA MONOLITHICS, INC., a California comporation

By: Name: / har 465 Title: Gyer VP4 Genera

ACCEPTED:

HSBC BANK USA, NATIONAL ASSOCIATION, as Administrative Agent

By: Name: Title:

ECLIFF JACKMAN

VICE PRESIDENT

PATENT REEL: 037284 FRAME: 0748 Schedule I

Registered U.S. Patents

RECORD OWNER: SENTICH CORPORATION

Record Owner	33	Application No.	Filing Date	Pub No./ Registration No.	Pub. Bate/ Issue Bate	Status
Semtech Corporation	Capacitive Proximity Sensor and Mobile Device	14/824,294	8/12/2015		المتعاد ووجوان معاولات فيقوا والأواز ووجوان الجزاء والما	Pending
Semtech Corporation	Descrialized Dual-Loop Clock and Data Recovery Circuit	14/871,719	9/30/2015		e e e e e e e e e e e e e e e e e e e	Pending
Semtech Corporation	Glass/ceramics replacement of epoxy for high temperature hermetically scaled non-axial electronic packages	(Continuation) 14/827,142	8/14/2015			Pending
Semtech Corporation	Measuring Circuit and Measuring Method for a Capacitive Touch-Sensitive Panel	14/755,343	6/30/2015			Pending
Semtech Corporation	Ranging and Positioning System	(Continuation) 14/767,363	8/12/2015			Pending
Semtech Corporation	Sampling Circuitry and Sampling Method for Plurality of Electrodes	14/755,850	7/16/2015			Pending
Semtech Corporation	Semiconductor Device and Method of Encapsulating Semiconductor Die	14/810,254	7/27/2015			Pending
Serntech Corporation	Semiconductor Device and Method of Forming Small Z Semiconductor Die	14/814,384	7/30/2015			Pending
Semtech Corporation	Semiconductor Device and Method for Forming Inverted Pyramid Cavity Semiconductor Package	14/825,110	8/12/2015			Pending
Semtech Corporation	Signal Concentrator Device	14/755,602	6/30/2015			Pending

SMRH:441179789.2

κģ

PATENT REEL: 037284 FRAME: 0749